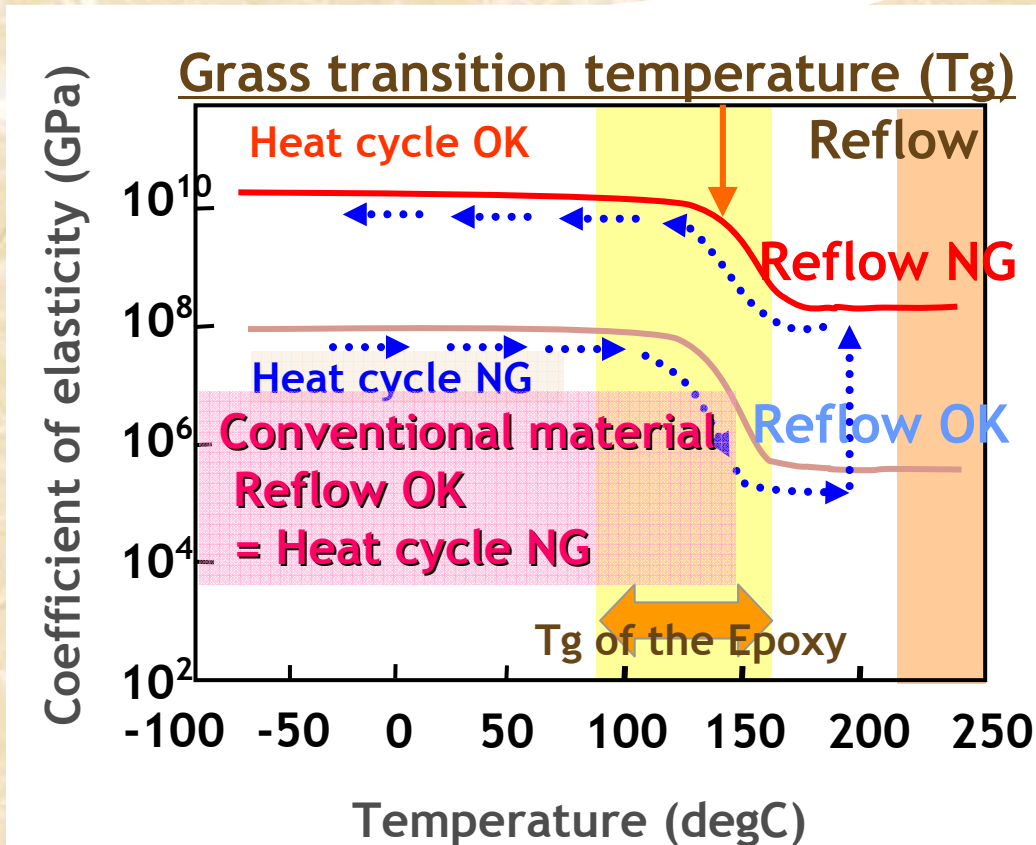


Underfill - “2-step hardening” Underfill

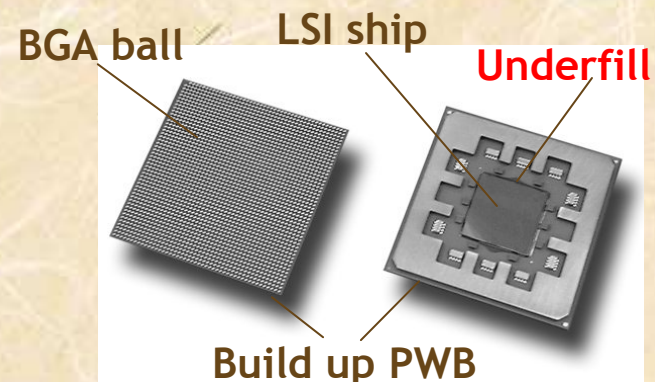
Bear chip mount (Solder bump)

No ideal material that overcomes both stress; the reflow / heat cycle

“2-step hardening” Underfill



1st step: Type 1 resin is set
(Low elasticity in reflow)
2nd step: Type 2 resin is set
(High elasticity at room temp)



For the low-cost PWB (with low cost resin)

Nobuhiro Imaizumi etc, “New Under-fill Adhesive for Flip Chip BGA”,
2004 Proceeding “Pan Pacific Microelectronics Symposium”, pp45-50(2004)